INTEGRATED CIRCUITS



Product specification Supersedes data of 1995 Sep 18 IC23 Data Handbook 1998 Feb 25



Philips Semiconductors

74ABT16541 74ABTH16541

FEATURES

- Power-up 3-State
- \bullet Multiple V_{CC} and GND pins minimize switching noise
- Provides ideal interface and increases fan-out of MOS Microprocessors
- 3-State buffers sink 64mA and source 32mA
- 74ABTH16541 incorporates bus-hold data inputs which eliminate the need for external pull-up resistors to hold unused inputs
- Latch-up protection exceeds 500mA per Jedec Std 17
- ESD protection exceeds 2000 V per MIL STD 883 Method 3015 and 200 V per Machine Model
- Two 8-bit bus interfaces
- Bus-hold data inputs eliminate the need for external pull-up resistors to hold unused inputs

QUICK REFERENCE DATA

DESCRIPTION

The 74ABT16541 high-performance BiCMOS device combines low static and dynamic power dissipation with high speed and high output drive.

The 74ABT16541 has two octal buffers that are ideal for driving bus lines. The outputs are all capable of sinking 64mA and sourcing 32mA.

Two options are available, 74ABT16541 which does not have the bus-hold feature and 74ABTH16541 which incorporates the bus-hold feature.

SYMBOL	PARAMETER	CONDITIONS T _{amb} = 25°C; GND = 0V	TYPICAL	UNIT
^t PLH ^t PHL	Propagation delay nAx to nYx	$C_{L} = 50 pF; V_{CC} = 5V$	2.0 1.5	ns
C _{IN}	Input capacitance	$V_I = 0V \text{ or } V_{CC}$	4	pF
C _{OUT}	Output capacitance	$V_{O} = 0V \text{ or } V_{CC}$; 3-State	6	pF
I _{CCZ}		Outputs disabled; V_{CC} =5.5V	500	μΑ
I _{CCL}	Quiescent supply current	Outputs LOW; $V_{CC} = 5.5V$	8	mA

ORDERING INFORMATION

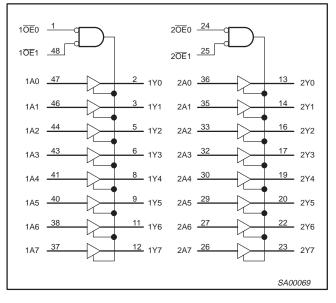
PACKAGES	TEMPERATURE RANGE	OUTSIDE NORTH AMERICA	NORTH AMERICA	DWG NUMBER
48-Pin Plastic SSOP Type III	–40°C to +85°C	74ABT16541 DL	BT16541 DL	SOT370-1
48-Pin Plastic TSSOP Type II	–40°C to +85°C	74ABT16541 DGG	BT16541 DGG	SOT362-1
48-Pin Plastic SSOP Type III	–40°C to +85°C	74ABTH16541 DL	BH16541 DL	SOT370-1
48-Pin Plastic TSSOP Type II	–40°C to +85°C	74ABTH16541 DGG	BH16541 DGG	SOT362-1

PIN DESCRIPTION

PIN NUMBER	SYMBOL	NAME AND FUNCTION
47, 46, 44, 43, 41, 40, 38, 37, 36, 35, 33, 32, 30, 29, 27, 26	1A0 - 1A7 2A0 - 2A7	Data inputs
2, 3, 5, 6, 8, 9, 11, 12, 13, 14, 16, 17 19, 20, 22, 23	1Y0 - 1Y7, 2Y0 - 2Y7	Data outputs
1, 48 24, 25	1 <u>0E</u> 0, 1 <u>0E</u> 1, 20E0, 20E1	Output enables
4, 10, 15, 21 28, 34, 39, 45	GND	Ground (0V)
7, 18, 31, 42	V _{CC}	Positive supply voltage

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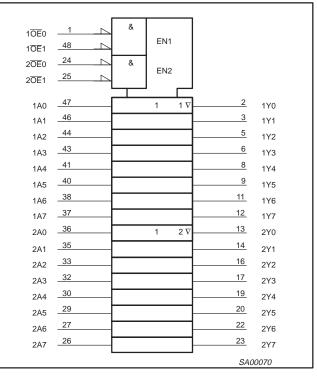
LOGIC SYMBOL



PIN CONFIGURATION

		7	
1 0E 0	1	48	1 0E 1
1Y0	2	47	1A0
1Y1	3	46	1A1
GND	4	45	GND
1Y2	5	44	1A2
1Y3	6	43	1A3
Vcc	7	42	VCC
1Y4	8	41	1A4
1Y5	9	40	1A5
GND	10	39	GND
1Y6	11	38	1A6
1Y7	12	37	1A7
2Y0	13	36	2A0
2Y1	14	35	2A1
GND	15	34	GND
2Y2	16	33	2A2
2Y3	17	32	2A3
Vcc	18	31	VCC
2Y4	19	30	2A4
2Y5	20	29	2A5
GND	21	28	GND
2Y6	22	27	2A6
2Y7	23	26	2A7
2 0E 0	24	25	2 0E 1
	L	J SA	00068
L		0A	

LOGIC SYMBOL (IEEE/IEC)



FUNCTION TABLE

	INPUTS	OUTPUTS	
n <mark>OE</mark> 0	n <mark>OE</mark> 1	nlx	nYx
L	L	L	L
L	L	н	н
х	н	х	Z
Н	Х	Х	Z

H = HIGH voltage level

= LOW voltage level L = D0n't care

X = D0n't care Z = High impedance "off" state

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ABSOLUTE MAXIMUM RATINGS^{1, 2}

SYMBOL	PARAMETER	CONDITIONS	RATING	UNIT
V _{CC}	DC supply voltage		-0.5 to +7.0	V
I _{IK}	DC input diode current	V ₁ < 0	-18	mA
VI	DC input voltage ³		-1.2 to +7.0	V
I _{ОК}	DC output diode current	V _O < 0	-50	mA
V _{OUT}	DC output voltage ³	output in Off or High state	-0.5 to +5.5	V
I _{OUT}	DC output current	output in Low state	128	mA
T _{stg}	Storage temperature range		-65 to 150	°C

NOTES:

 Stresses beyond those listed may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

 The performance capability of a high-performance integrated circuit in conjunction with its thermal environment can create junction temperatures which are detrimental to reliability. The maximum junction temperature of this integrated circuit should not exceed 150°C.

3. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

RECOMMENDED OPERATING CONDITIONS

SYMBOL	PARAMETER	LIM	ITS	
STMBOL	FARAWETER	Min	Max	VIII V V V V
V _{CC}	DC supply voltage	4.5	5.5	V
VI	Input voltage	0	V _{CC}	V
V _{IH}	High-level input voltage	2.0		V
V _{IL}	Low-level Input voltage		0.8	V
I _{ОН}	High-level output current		-32	mA
I _{OL}	Low-level output current		64	mA
Δt/Δv	Input transition rise or fall rate	0	10	ns/V
T _{amb}	Operating free-air temperature range	-40	+85	°C

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DC ELECTRICAL CHARACTERISTICS

						LIMITS			
SYMBOL	PARAMETER	TEST CONDITIONS		Та	_{mb} = +25	°C		-40°C 85°C	UNIT
				Min	Тур	Max	Min	Max	
V _{IK}	Input clamp voltage	V _{CC} = 4.5V; I _{IK} = -18mA			-0.9	-1.2		-1.2	V
		V _{CC} = 4.5V; I _{OH} = -3mA; V _I = V	′ _{IL} or V _{IH}	2.5	2.9		2.5		V
V _{OH}	High-level output voltage	$V_{CC} = 5.0V; I_{OH} = -3mA; V_{I} = V$	′ _{IL} or V _{IH}	3.0	3.4		3.0		V
		V_{CC} = 4.5V; I_{OH} = -32mA; V_{I} =	V _{IL} or V _{IH}	2.0	2.4		2.0		V
V _{OL}	Low-level output voltage	$V_{CC} = 4.5$ V; $I_{OL} = 64$ mA; $V_{I} = V$	_{IL} or V _{IH}		0.42	0.55		0.55	V
I	Input leakage current	V_{CC} = 5.5V; V_I = GND or 5.5V			±0.01	±1.0		±1.0	μΑ
	Input leakage current	V_{CC} = 5.5V; V_{I} = V_{CC} or GND	Control pins		±0.01	±1		±1	μA
I	74ABTH16541	$V_{CC} = 5.5 V; V_{I} = V_{CC}$	Data pins		0.01	1		1	μΑ
		$V_{CC} = 5.5 V; V_{I} = 0$	Data pins		-2	-3		-5	μΑ
	Due Hald summer 1 A tanuta 3	$V_{CC} = 4.5 V; V_{I} = 0.8 V$		50			50		
I _{HOLD}	Bus Hold current A inputs ³ 74ABTH16541	$V_{CC} = 4.5 V; V_{I} = 2.0 V$		-75			-75		μΑ
		$V_{CC} = 5.5$ V; $V_{I} = 0$ to 5.5V		±500					
I _{OFF}	Power-off leakage current	V_{CC} = 0.0V; V_O or $V_I \leq 4.5V$			±5.0	±100		±100	μΑ
I _{PU} /I _{PD}	Power-up/down 3-State output current	$V_{\underline{CC}} = 2.0V; V_{\underline{O}} = 0.5V; V_{\underline{I}} = GN$ $V_{\underline{OE}} = V_{\underline{CC}}$	ID or V _{CC} ;		±5.0	±50		±50	μΑ
I _{OZH}	3-State output High current	$V_{CC} = 5.5$ V; $V_{O} = 2.7$ V; $V_{I} = V_{IL}$	or V _{IH}		1.0	10		10	μΑ
I _{OZL}	3-State output Low current	$V_{CC} = 5.5$ V; $V_{O} = 0.5$ V; $V_{I} = V_{IL}$	or V _{IH}		-1.0	-10		-10	μΑ
I _{CEX}	Output high leakage current	$V_{CC} = 5.5$ V; $V_{O} = 5.5$ V; $V_{I} = GN$	ID or V _{CC}		1.0	50		50	μΑ
Ι _Ο	Output current ¹	$V_{CC} = 5.5 V; V_{O} = 2.5 V$		-50	-70	-180	-50	-180	mA
I _{CCH}		V_{CC} = 5.5V; Outputs High, V _I =	GND or V _{CC}		0.5	1.0		1.0	mA
I _{CCL}	Quiescent supply current	$V_{CC} = 5.5V$; Outputs Low, $V_I = 0$	GND or V _{CC}		8	19		19	mA
I _{CCZ}		V_{CC} = 5.5V; Outputs 3-State; V _I = GND or V _{CC}			0.5	1.0		1.0	mA
ΔI_{CC}	Additional supply current per input pin ² 74ABT16541	Outputs enabled, one input at 3 inputs at V_{CC} or GND; V_{CC} = 5.	.4V, other 5V		100	250		250	μΑ
ΔI_{CC}	Additional supply current per input pin ² 74ABTH16541	Outputs enabled, one input at 3 inputs at V_{CC} or GND; V_{CC} = 5.	.4V, other 5V		0.2	1.0		1.0	mA

NOTES:

Not more than one output should be tested at a time, and the duration of the test should not exceed one second.
This is the increase in supply current for each input at 3.4V.

3. This is the bus hold overdrive current required to force the input to the opposite logic state.

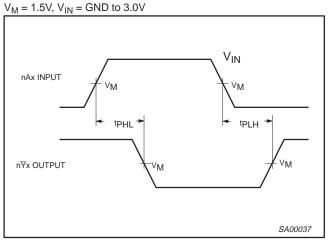
AC CHARACTERISTICS

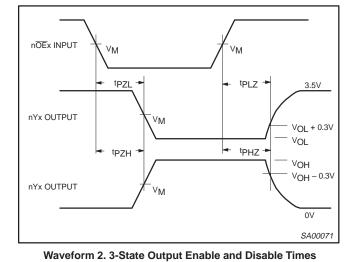
GND = 0V; $t_R = t_F$ = 2.5ns; C_L = 50pF, R_L = 500 Ω

			LIMITS					
SYMBOL	PARAMETER	WAVEFORM	T _a V	amb = +25° ′CC = +5.0′	C V	$T_{amb} = -40^{\circ}$ $V_{CC} = +5.$	°C to +85°C .0V ±0.5V	UNIT
			Min	Тур	Max	Min	Max	
t _{PLH} t _{PHL}	Propagation delay nIx to nYx	1	1.0 1.0	2.0 1.5	3.0 3.6	1.0 1.0	3.4 4.2	ns
t _{PZH} t _{PZL}	Output enable time to High and Low level	2	1.3 1.6	2.9 3.1	4.3 4.7	1.3 1.6	5.2 6.0	ns
t _{PHZ} t _{PLZ}	Output disable time from High and Low level	2	1.3 1.0	3.5 2.8	4.4 3.6	1.3 1.0	5.1 3.9	ns

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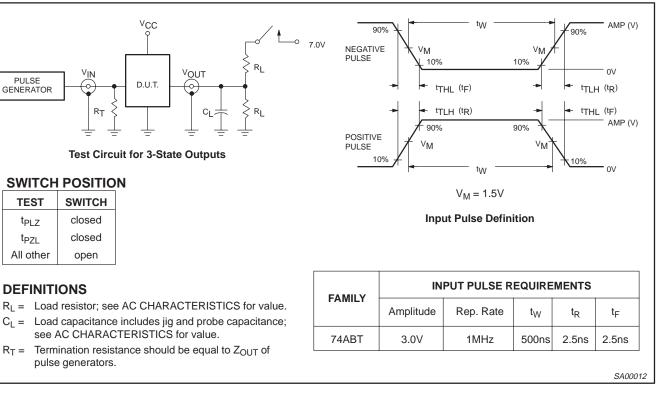
AC WAVEFORMS



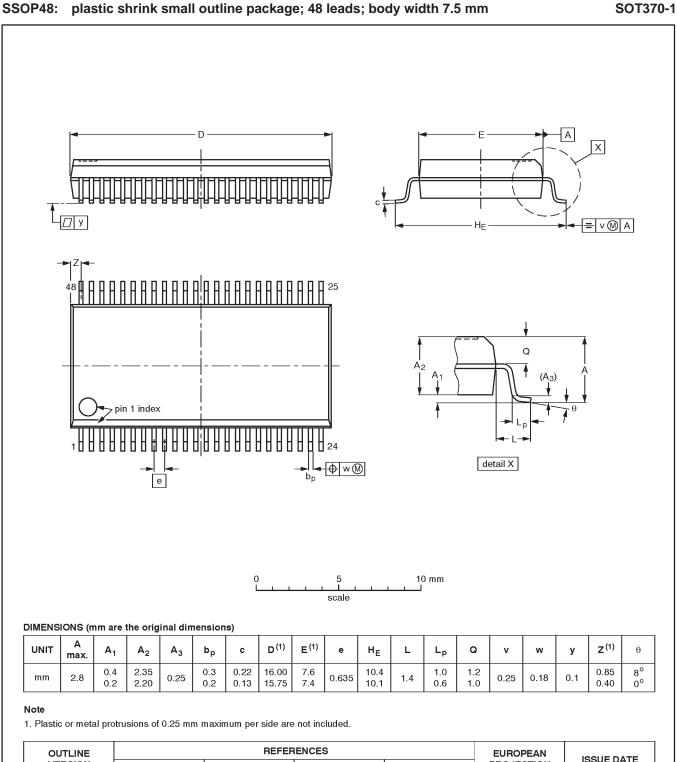


Waveform 1. Input (An) to Output (Yn) Propagation Delays

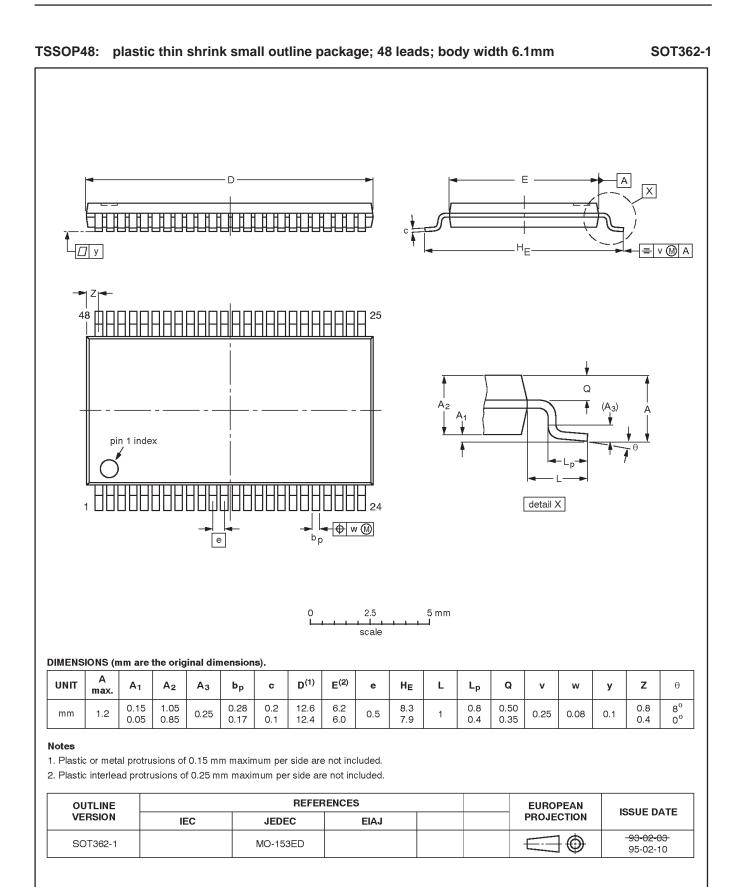
TEST CIRCUIT AND WAVEFORMS



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NOTES

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Data sheet status

Data sheet status	Product status	Definition ^[1]
Objective specification	Development	This data sheet contains the design target or goal specifications for product development. Specification may change in any manner without notice.
Preliminary specification	Qualification	This data sheet contains preliminary data, and supplementary data will be published at a later date. Philips Semiconductors reserves the right to make chages at any time without notice in order to improve design and supply the best possible product.
Product specification	Production	This data sheet contains final specifications. Philips Semiconductors reserves the right to make changes at any time without notice in order to improve design and supply the best possible product.

[1] Please consult the most recently issued datasheet before initiating or completing a design.

Definitions

Short-form specification — The data in a short-form specification is extracted from a full data sheet with the same type number and title. For detailed information see the relevant data sheet or data handbook.

Limiting values definition — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

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